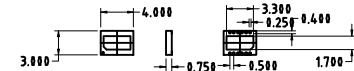
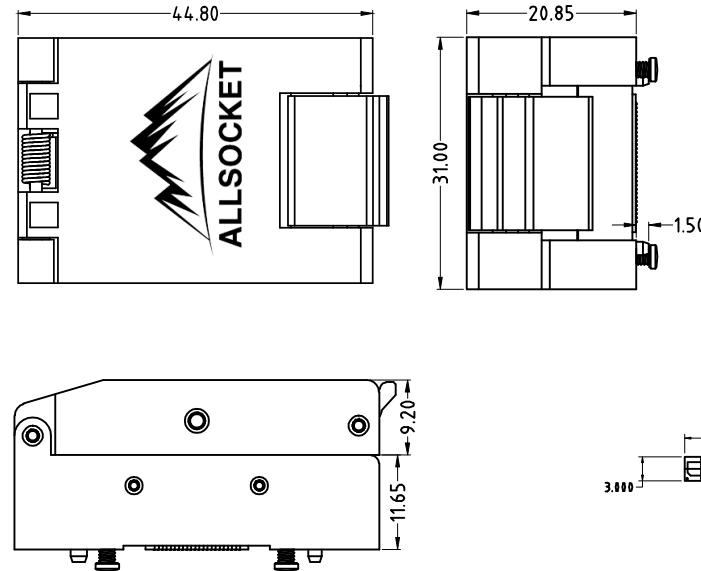


SEC.A-A




Chip

1. MATERIAL AND FINISH

1. SOCKET LID :PEI
2. SOCKET BASE :PEI
3. CONTACTS :BeCu,SELECTIVE Au-AuFLASH OVER NI PLATING
4. SPRINGS :STAINLESS STEEL ,PASSIVATED

2. PERFORMANCE

1. Insulation Resistance : 1000MΩ or more at DC 100V
2. Dielectric Withstanding Voltage: 100V AC for one minute
3. Contact Resistance 80mΩ, MAX. at 10mA and 20mV MAX.(Initial)
4. Operation Temperature -50°C~+150°C
5. Life Span 10,000 Times (Mechanical)
6. Operation Force 3.0 Kg MAX

△C				DWG NO			PART NAME	ASS51-XGA12-(4X3)-0.5-CL
△B				MATERIAL	SCALE	1:1	TITLE	
△A				QTY	1	UNIT	MM	
REV	DESCRIPTION	DATE	CHECK	SHEET	1 OF 1	REV	01	
APPLICATION				APPROVE		DATE		
APPROVE	DESIGN	DATE	CHECK	DATE	DATE	<div> ALLSOCKET www.allsocket.com sales@allsocket.com</div>		
ALL UNFINISHED DIMENSIONS				TRIC	DESIGN			


 www.allsocket.com
 sales@allsocket.com